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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

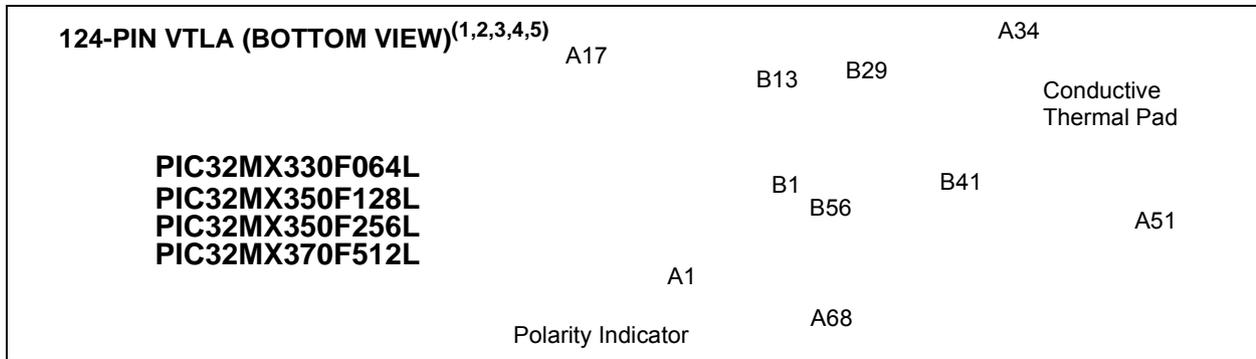
### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	49
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic32mx470f512ht-i-pt">https://www.e-xfl.com/product-detail/microchip-technology/pic32mx470f512ht-i-pt</a>

# PIC32MX330/350/370/430/450/470

**TABLE 6: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)**



Package Bump #	Full Pin Name	Package Bump #	Full Pin Name
B7	MCLR	B32	SDA2/RA3
B8	Vss	B33	TDO/RA5
B9	TMS/CTED1/RA0	B34	OSC1/CLKI/RC12
B10	RPE9/RE9	B35	No Connect
B11	AN4/C1INB/RB4	B36	RPA14/RA14
B12	Vss	B37	RPD8/RTCC/RD8
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	B38	RPD10/PMCS2/RD10
B14	PGED1/AN0/RPB0/RB0	B39	RPD0/RD0
B15	No Connect	B40	SOSCO/RPC14/T1CK/RC14
B16	PGED2/AN7/RPB7/CTED3/RB7	B41	Vss
B17	VREF+/CVREF+/PMA6/RA10	B42	AN25/RPD2/RD2
B18	AVss	B43	RPD12/PMD12/RD12
B19	AN9/RPB9/CTED4/RB9	B44	RPD4/PMWR/RD4
B20	AN11/PMA12/RB11	B45	PMD14/RD6
B21	VDD	B46	No Connect
B22	RPF13/RF13	B47	No Connect
B23	AN12/PMA11/RB12	B48	VCAP
B24	AN14/RPB14/CTED5/PMA1/RB14	B49	RPF0/PMD11/RF0
B25	Vss	B50	RPG1/PMD9/RG1
B26	RPD14/RD14	B51	TRCLK/RA6
B27	RPF4/PMA9/RF4	B52	PMD0/RE0
B28	No Connect	B53	VDD
B29	RPF8/RF8	B54	TRD2/RG14
B30	RPF6/SCKI/INT0/RF6	B55	TRD0/RG13
B31	SCL1/RG2	B56	RPE3/CTPLS/PMD3/RE3

- Note**
- 1: The RPN pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.
  - 2: Every I/O port pin (RAX-RGx), with the exception of RF6, can be used as a change notification pin (CNAX-CNGx). See **Section 12.0 "I/O Ports"** for more information.
  - 3: RPF6 (bump B30) and RPF7 (bump A37) are only remappable for input functions.
  - 4: Shaded package bumps are 5V tolerant.
  - 5: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

# PIC32MX330/350/370/430/450/470

## 2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- $C_{IN}$  = PIC32\_OSC2\_Pin Capacitance = ~4-5 pF
- $C_{OUT}$  = PIC32\_OSC1\_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e., 12 mm length) = 2.5 pF

### EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended:  $C1 = C2 = 15 \text{ pF}$

Therefore:

$$\begin{aligned}
 C_{LOAD} &= \{ ([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \} \\
 &\quad + \text{estimated oscillator PCB stray capacitance} \\
 &= \{ ([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5 \text{ pF} \\
 &= \{ ([20][20]) / [40] \} + 2.5 \\
 &= 10 + 2.5 = 12.5 \text{ pF}
 \end{aligned}$$

Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals "C1" and "C2".

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

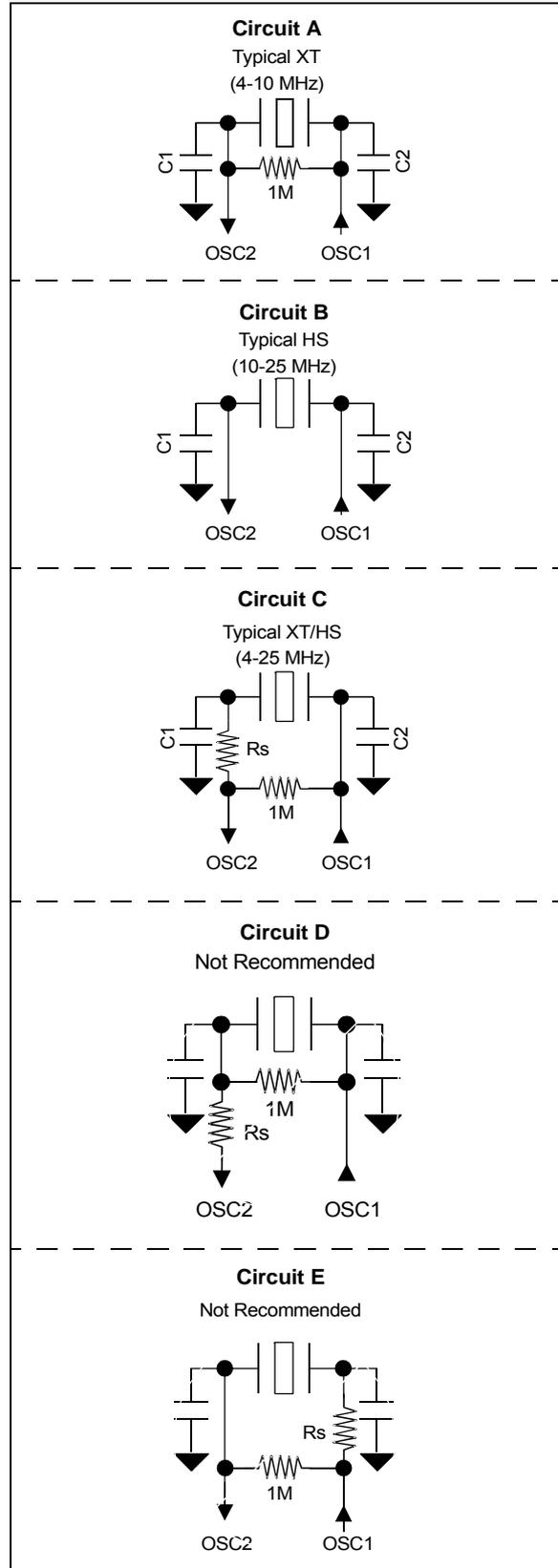
- Select a crystal with a lower "minimum" power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing "ESR" rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

**Note:** Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor,  $R_S$ , as shown in circuit "C" in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to  $\sim V_{DD} - 0.6V$ . When measuring the oscillator signal you must use a FET scope probe or a probe with  $\leq 1.5 \text{ pF}$  or the scope probe itself will unduly change the gain and peak-to-peak levels.

#### 2.8.1.1 Additional Microchip References

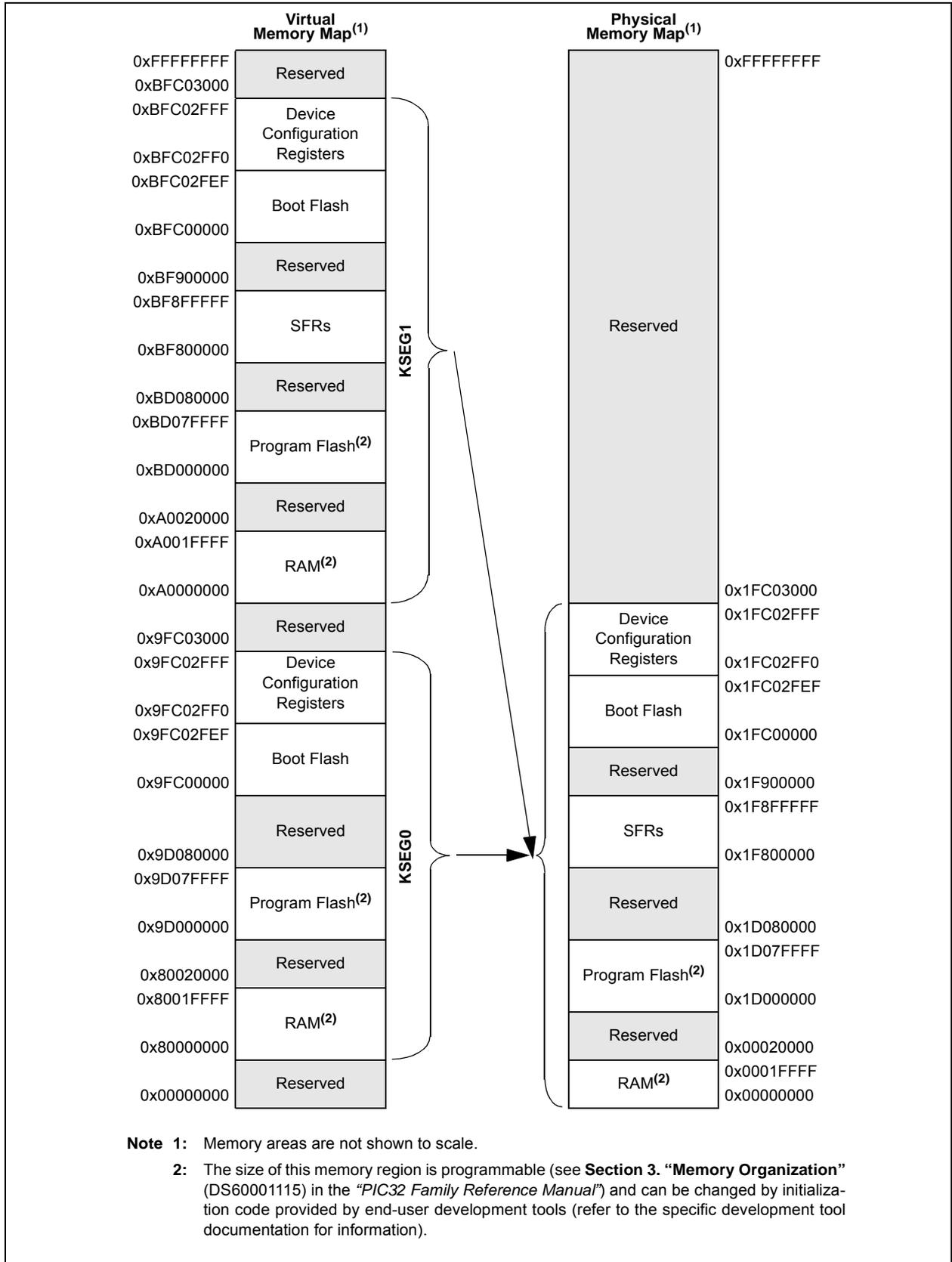
- AN588 "PICmicro® Microcontroller Oscillator Design Guide"
- AN826 "Crystal Oscillator Basics and Crystal Selection for rPIC™ and PICmicro® Devices"
- AN849 "Basic PICmicro® Oscillator Design"

**FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS**



# PIC32MX330/350/370/430/450/470

**FIGURE 4-4: MEMORY MAP FOR DEVICES WITH 512 KB OF PROGRAM MEMORY**



## 7.0 INTERRUPT CONTROLLER

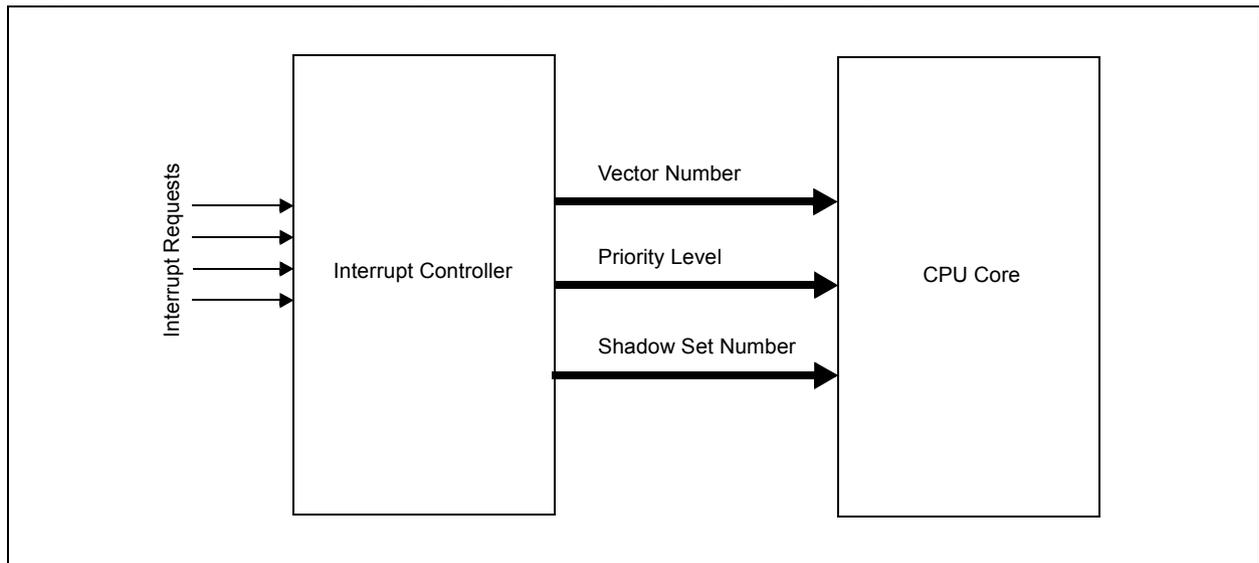
**Note:** This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. “Interrupt Controller”** (DS60001108), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site ([www.microchip.com/pic32](http://www.microchip.com/pic32)).

PIC32MX330/350/370/430/450/470 devices generate interrupt requests in response to interrupt events from peripheral modules. The interrupt control module exists externally to the CPU logic and prioritizes the interrupt events before presenting them to the CPU.

The PIC32MX330/350/370/430/450/470 interrupt module includes the following features:

- Up to 76 interrupt sources
- Up to 46 interrupt vectors
- Single and multi-vector mode operations
- Five external interrupts with edge polarity control
- Interrupt proximity timer
- Seven user-selectable priority levels for each vector
- Four user-selectable subpriority levels within each priority
- Dedicated shadow set configurable for any priority level (see the FSRSEL<2:0> bits (DEVCFG3<18:16>) in **28.0 “Special Features”** for more information)
- Software can generate any interrupt
- User-configurable interrupt vector table location
- User-configurable interrupt vector spacing

**FIGURE 7-1: INTERRUPT CONTROLLER MODULE BLOCK DIAGRAM**



# PIC32MX330/350/370/430/450/470

## REGISTER 11-12: U1ADDR: USB ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	LSPDEN	DEVADDR<6:0>						

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **LSPDEN:** Low Speed Enable Indicator bit

1 = Next token command to be executed at Low Speed

0 = Next token command to be executed at Full Speed

bit 6-0 **DEVADDR<6:0>:** 7-bit USB Device Address bits

## REGISTER 11-13: U1FRML: USB FRAME NUMBER LOW REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	FRML<7:0>							

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **FRML<7:0>:** The 11-bit Frame Number Lower bits

The register bits are updated with the current frame number whenever a SOF TOKEN is received.

**TABLE 12-7: PORTD REGISTER MAP FOR PIC32MX330F064L, PIC32MX350F128L, PIC32MX350F256L, PIC32MX370F512L, PIC32MX430F064L, PIC32MX450F128L, PIC32MX450F256L, AND PIC32MX470F512L DEVICES ONLY**

Virtual Address (BF88_#)	Register Name <sup>(1)</sup>	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6300	ANSELD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
6310	TRISD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISD15	TRISD14	TRISD13	TRISD12	TRISD11	TRISD10	TRISD9	TRISD8	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	xxxx
5320	PORTD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RD15	RD14	RD13	RD12	RD11	RD10	RD9	RD8	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx
6330	LATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATD15	LATD14	LATD13	LATD12	LATD11	LATD10	LATD9	LATD8	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	xxxx
6340	ODCD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCD15	ODCD14	ODCD13	ODCD12	ODCD11	ODCD10	ODCD9	ODCD8	ODCD7	ODCD6	ODCD5	ODCD4	ODCD3	ODCD2	ODCD1	ODCD0	xxxx
6350	CNPUD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPUD15	CNPUD14	CNPUD13	CNPUD12	CNPUD11	CNPUD10	CNPUD9	CNPUD8	CNPUD7	CNPUD6	CNPUD5	CNPUD4	CNPUD3	CNPUD2	CNPUD1	CNPUD0	xxxx
6360	CNPDD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPDD15	CNPDD14	CNPDD13	CNPDD12	CNPDD11	CNPDD10	CNPDD9	CNPDD8	CNPDD7	CNPDD6	CNPDD5	CNPDD4	CNPDD3	CNPDD2	CNPDD1	CNPDD0	xxxx
6370	CNCOND	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6380	CNEND	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNIED15	CNIED14	CNIED13	CNIED12	CNIED11	CNIED10	CNIED9	CNIED8	CNIED7	CNIED6	CNIED5	CNIED4	CNIED3	CNIED2	CNIED1	CNIED0	xxxx
6390	CNSTATD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNS TATD15	CN STATD14	CN STATD13	CN STATD12	CN STATD11	CN STATD10	CN STATD9	CN STATD8	CN STATD7	CN STATD6	CN STATD5	CN STATD4	CN STATD3	CN STATD2	CN STATD1	CN STATD0	xxxx

**Legend:** x = Unknown value on Reset; — = Unimplemented, read as '0'; Reset values are shown in hexadecimal.

**Note 1:** All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 “CLR, SET, and INV Registers”** for more information.

TABLE 12-18: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits														All Resets		
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2		17/1	16/0
FCA0	RPG8R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPG8<3:0>				0000
FCA4	RPG9R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPG9<3:0>				0000

**Legend:** x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

- Note**
- 1: This register is not available on 64-pin devices.
  - 2: This register is only available on devices without a USB module.
  - 3: This register is not available on 64-pin devices with a USB module.



## REGISTER 16-1: ICxCON: INPUT CAPTURE 'x' CONTROL REGISTER (CONTINUED)

bit 2-0

**ICM<2:0>**: Input Capture Mode Select bits

111 = Interrupt-Only mode (only supported while in Sleep mode or Idle mode)

110 = Simple Capture Event mode – every edge, specified edge first and every edge thereafter

101 = Prescaled Capture Event mode – every sixteenth rising edge

100 = Prescaled Capture Event mode – every fourth rising edge

011 = Simple Capture Event mode – every rising edge

010 = Simple Capture Event mode – every falling edge

001 = Edge Detect mode – every edge (rising and falling)

000 = Input Capture module is disabled

**Note 1:** When using 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSClk cycle immediately following the instruction that clears the module's ON bit.

## 18.1 Control Registers

TABLE 18-1: SPI2 AND SPI2 REGISTER MAP

Virtual Address (BF80_#)	Register Name <sup>(1)</sup>	Bit Range	Bits														All Resets		
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2		17/1	16/0
5800	SPI1CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>	SRXISEL<1:0>	—	—	0000
5810	SPI1STAT	31:16	—	—	—	RXBUFELM<4:0>				—	—	—	TXBUFELM<4:0>				0000		
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	19EB
5820	SPI1BUF	31:16	DATA<31:0>														0000		
		15:0	DATA<31:0>														0000		
5830	SPI1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BRG<8:0>								0000
5840	SPI1CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>	—	0000
5A00	SPI2CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>	SRXISEL<1:0>	—	—	0000
5A10	SPI2STAT	31:16	—	—	—	RXBUFELM<4:0>				—	—	—	TXBUFELM<4:0>				0000		
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	19EB
5A20	SPI2BUF	31:16	DATA<31:0>														0000		
		15:0	DATA<31:0>														0000		
5A30	SPI2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BRG<8:0>								0000
5A40	SPI2CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>	—	0000

**Legend:** x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

**Note 1:** All registers in this table except SPIxBUF have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.2 "CLR, SET, and INV Registers" for more information.

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NOTES:

## 25.0 COMPARATOR VOLTAGE REFERENCE (CVREF)

**Note:** This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 20. “Comparator Voltage Reference (CVREF)”** (DS60001109), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site ([www.microchip.com/pic32](http://www.microchip.com/pic32)).

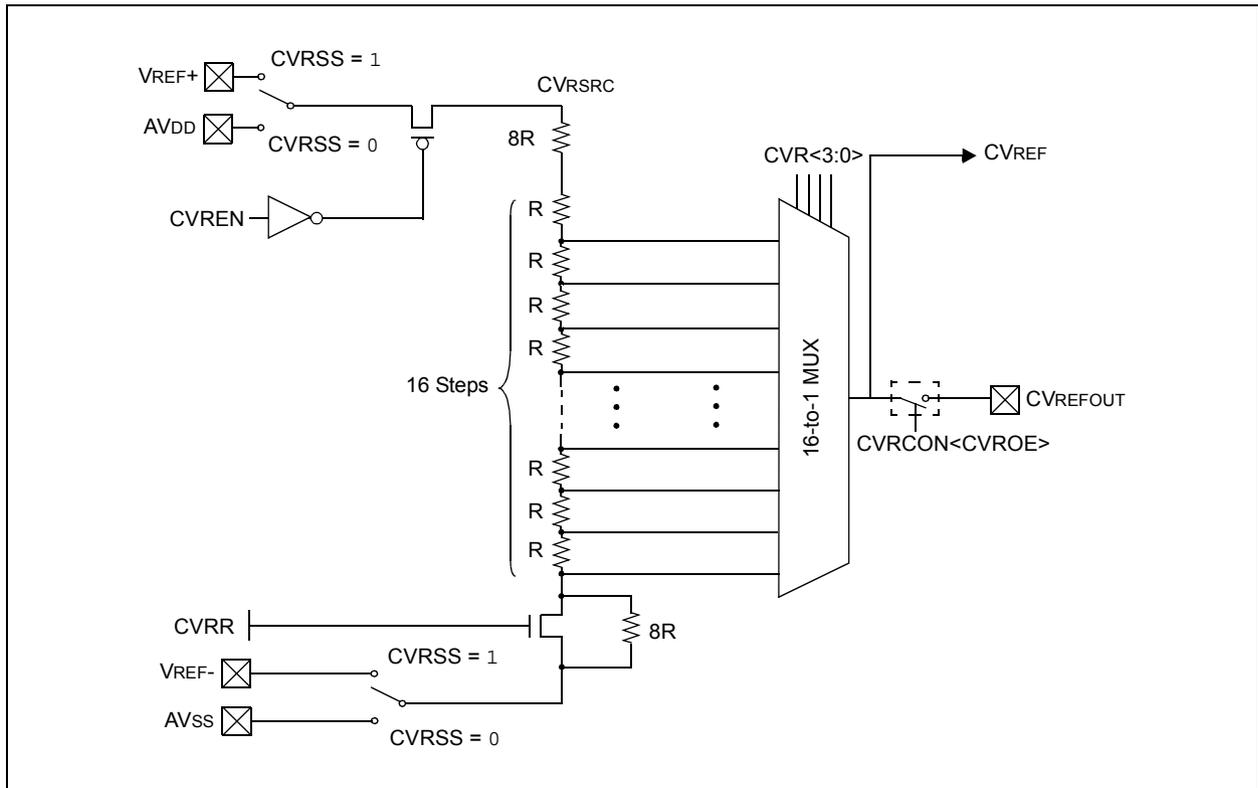
The CVREF module is a 16-tap, resistor ladder network that provides a selectable reference voltage. Although its primary purpose is to provide a reference for the analog comparators, it also may be used independently of them.

A block diagram of the module is illustrated in Figure 25-1. The resistor ladder is segmented to provide two ranges of voltage reference values and has a power-down function to conserve power when the reference is not being used. The module’s supply reference can be provided from either device VDD/VSS or an external voltage reference. The CVREF output is available for the comparators and typically available for pin output.

The CVREF module has the following features:

- High and low range selection
- Sixteen output levels available for each range
- Internally connected to comparators to conserve device pins
- Output can be connected to a pin

**FIGURE 25-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM**



## 25.1 Control Register

**TABLE 25-1: COMPARATOR VOLTAGE REFERENCE REGISTER MAP**

Virtual Address (BF80_#)	Register Name(*)	Bit Range	Bits															All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1		16/0
9800	CVRCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	—	CVROE	CVRR	CVRSS	CVR<3:0>			0000

**Legend:** x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

**Note 1:** The register in this table has corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 “CLR, SET, and INV Registers”** for more information.

# PIC32MX330/350/370/430/450/470

## REGISTER 28-6: DEVID: DEVICE AND REVISION ID REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0> <sup>(1)</sup>				DEVID<27:24> <sup>(1)</sup>			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16> <sup>(1)</sup>							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8> <sup>(1)</sup>							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0> <sup>(1)</sup>							

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-28 **VER<3:0>**: Revision Identifier bits<sup>(1)</sup>

bit 27-0 **DEVID<27:0>**: Device ID<sup>(1)</sup>

**Note 1:** See the "PIC32 Flash Programming Specification" (DS60001145) for a list of Revision and Device ID values.

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**TABLE 31-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)**

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Parameter No.	Typical <sup>(3)</sup>	Maximum	Units	Conditions	
<b>Operating Current (IDD)<sup>(1,2)</sup></b>					
DC20	2.5	4	mA	4 MHz	
DC21	6	9	mA	10 MHz <b>(Note 4)</b>	
DC22	11	17	mA	20 MHz <b>(Note 4)</b>	
DC23	21	32	mA	40 MHz <b>(Note 4)</b>	
DC24	30	45	mA	60 MHz <b>(Note 4)</b>	
DC25	40	60	mA	80 MHz	
DC25a	50	75	mA	100 MHz, -40°C ≤ TA ≤ +85°C	
DC25c	72	84	mA	120 MHz, 0°C ≤ TA ≤ +70°C	
DC26	100	—	μA	+25°C, 3.3V	LPRC (31 kHz) <b>(Note 4)</b>

**Note 1:** A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

**2:** The test conditions for IDD measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, program Flash, and SRAM data memory are operational, program Flash memory Wait states = 7, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
- No peripheral modules are operating (ON bit = 0), but the associated PMD bit is clear
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to Vss
- $\overline{\text{MCLR}} = \text{VDD}$
- CPU executing `while(1)` statement from Flash
- RTCC and JTAG are disabled

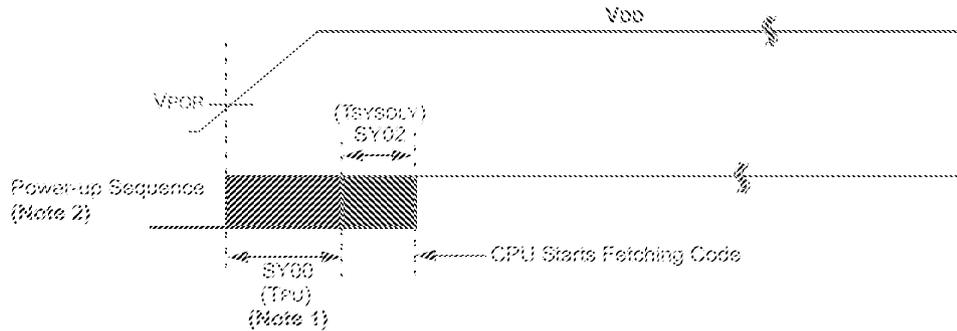
**3:** Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

**4:** This parameter is characterized, but not tested in manufacturing.

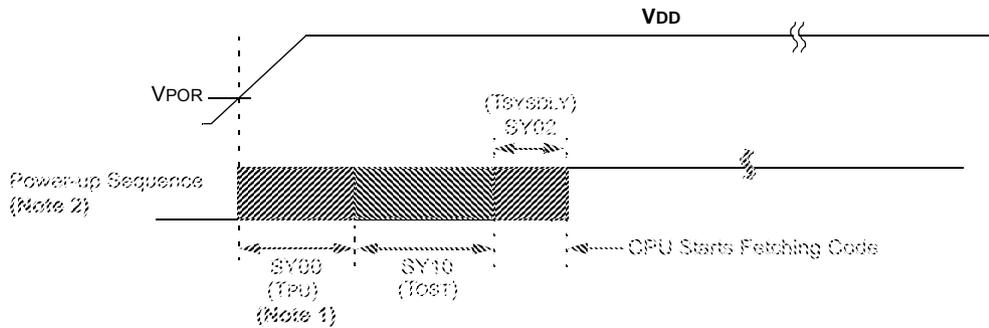
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**FIGURE 31-4: POWER-ON RESET TIMING CHARACTERISTICS**

*Internal Voltage Regulator Enabled*  
*Clock Sources = (FRC, FRCDIV, FRCDIV16, FRCPLL, EC, ECPLL and LPRC)*



*Internal Voltage Regulator Enabled*  
*Clock Sources = (HS, HSPLL, XT, XTPLL and Sosc)*

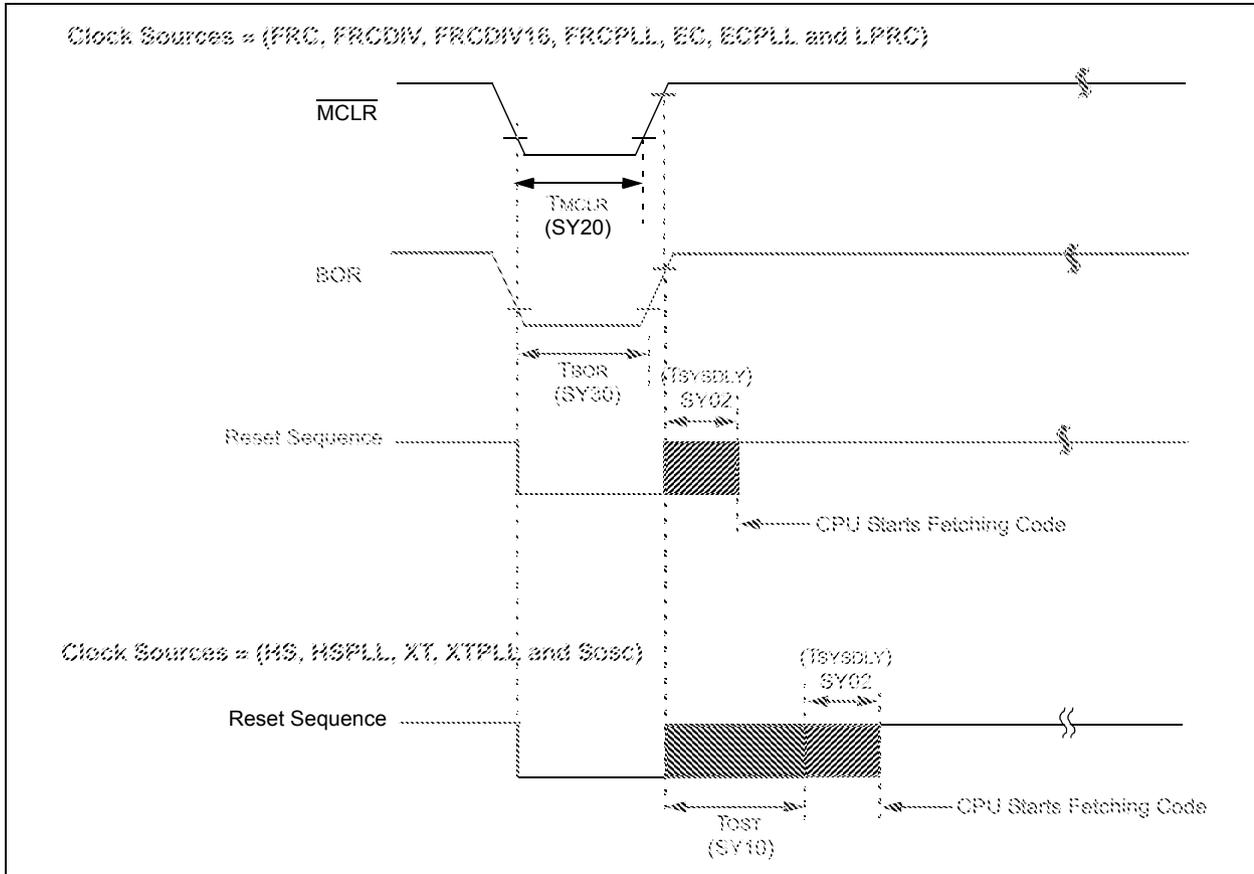


**Note 1:** The power-up period will be extended if the power-up sequence completes before the device exits from BOR ( $VDD < VDDMIN$ ).

**2:** Includes interval voltage regulator stabilization delay.

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**FIGURE 31-5: EXTERNAL RESET TIMING CHARACTERISTICS**



**TABLE 31-23: RESETS TIMING**

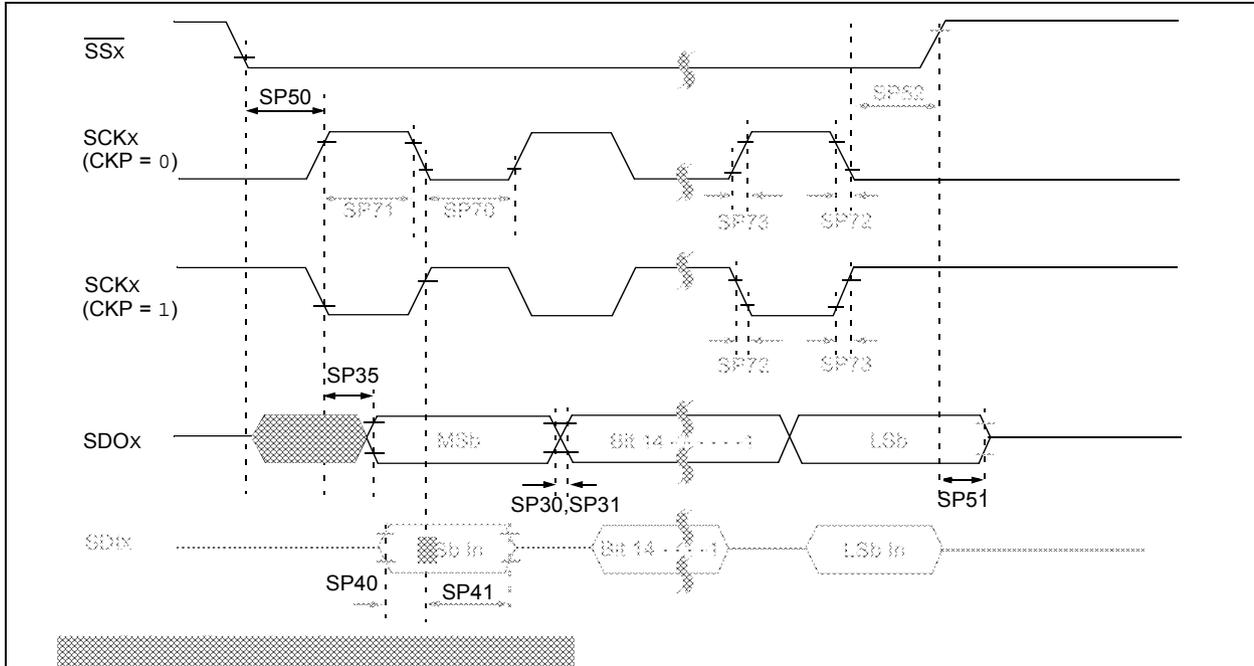
AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for Commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp				
Param. No.	Symbol	Characteristics <sup>(1)</sup>	Min.	Typical <sup>(2)</sup>	Max.	Units	Conditions
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	$\mu\text{s}$	—
SY02	TSYSDLY	System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched.	—	$1 \mu\text{s} +$ 8 SYSCLK cycles	—	—	—
SY20	TMCLR	MCLR Pulse Width (low)	2	—	—	$\mu\text{s}$	—
SY30	TBOR	BOR Pulse Width (low)	—	1	—	$\mu\text{s}$	—

**Note 1:** These parameters are characterized, but not tested in manufacturing.

**Note 2:** Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

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**FIGURE 31-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS**



**TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS**

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp					
Param. No.	Symbol	Characteristics <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Units	Conditions
SP70	TscL	SCKx Input Low Time ( <b>Note 3</b> )	T <sub>SCK</sub> /2	—	—	ns	—
SP71	Tsch	SCKx Input High Time ( <b>Note 3</b> )	T <sub>SCK</sub> /2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TDoF	SDOx Data Output Fall Time ( <b>Note 4</b> )	—	—	—	ns	See parameter DO32
SP31	TDoR	SDOx Data Output Rise Time ( <b>Note 4</b> )	—	—	—	ns	See parameter DO31
SP35	Tsch2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	V <sub>DD</sub> > 2.7V
			—	—	20	ns	V <sub>DD</sub> < 2.7V
SP40	TdIV2sch, TdIV2scl	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	Tsch2dIL, TscL2dIL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2sch, TssL2scl	SSx ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TssH2doZ	SSx ↑ to SDOx Output High-Impedance ( <b>Note 3</b> )	5	—	25	ns	—

**Note 1:** These parameters are characterized, but not tested in manufacturing.

**Note 2:** Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

**Note 3:** The minimum clock period for SCKx is 40 ns.

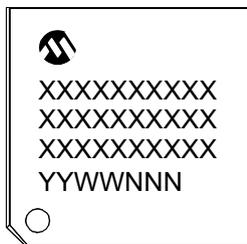
**Note 4:** Assumes 50 pF load on all SPIx pins.

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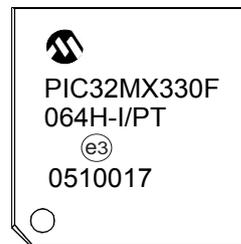
## 33.0 PACKAGING INFORMATION

### 33.1 Package Marking Information

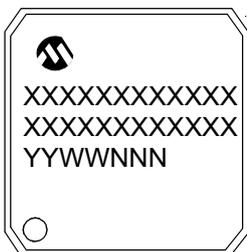
64-Lead TQFP (10x10x1 mm)



Example



100-Lead TQFP (14x14x1 mm)



Example



100-Lead TQFP (12x12x1 mm)



Example

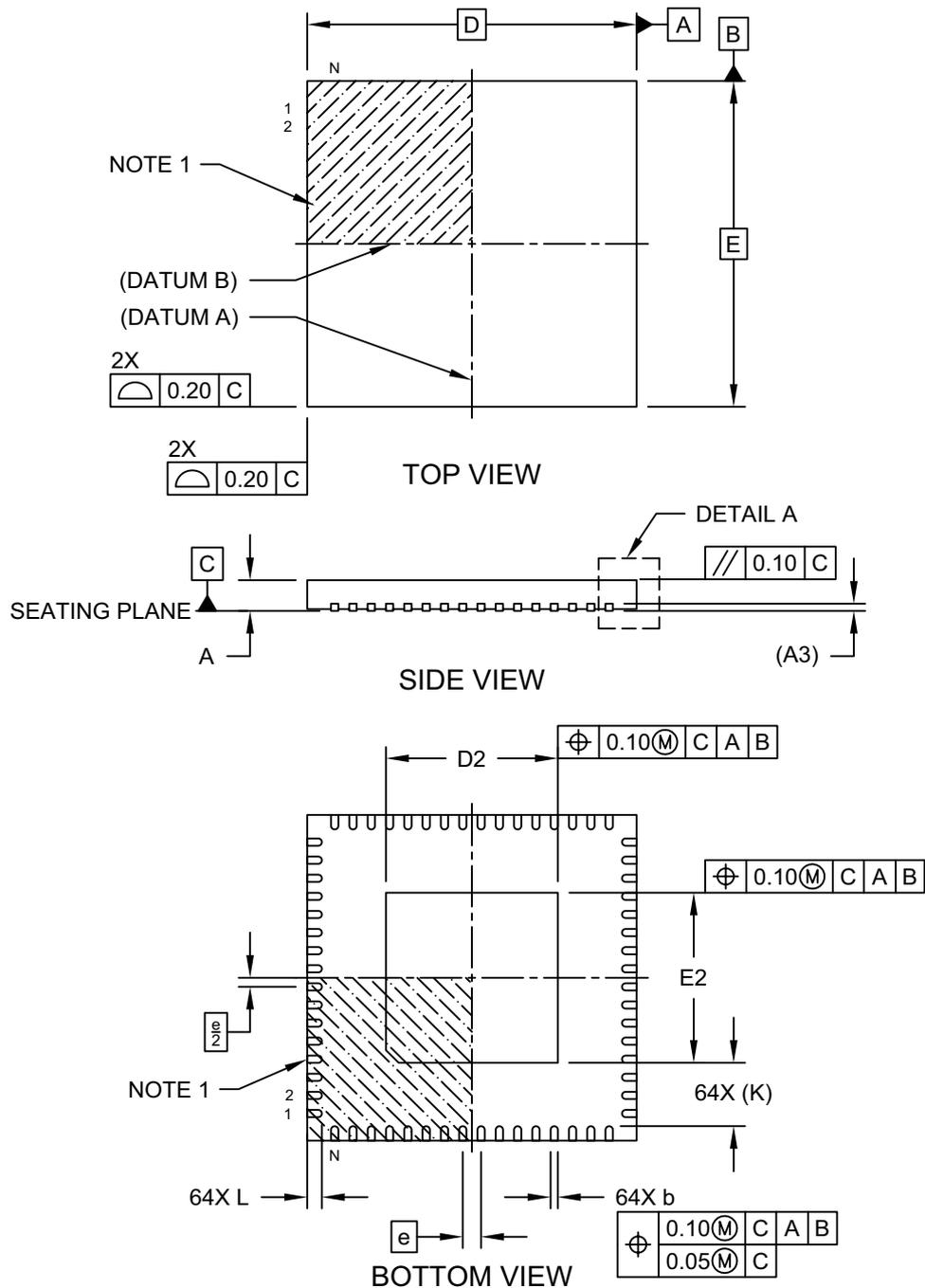


<b>Legend:</b>	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	*	Pb-free JEDEC designator for Matte Tin (Sn)
		This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
<b>Note:</b>	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.	

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## 64-Terminal Plastic Quad Flat Pack, No Lead (RG) 9x9x0.9 mm Body [QFN] Saw Singulated

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-260A Sheet 1 of 2